

POLISHING PAD AND METHOD FOR MANUFACTURING POLISHED
WORKPIECE

Abstract

A polishing pad including a polishing layer, and an end point detection window that is provided in an opening of the polishing layer, wherein in a dynamic viscoelasticity measurement which is performed under conditions of a tensile mode, a frequency of 1.6 Hz, 30 to 55°C, and a submerged state, a ratio (E'_{p40}/E'_{w40}) of a storage elastic modulus E'_{p40} of the polishing layer at 40°C to a storage elastic modulus E'_{w40} of the end point detection window at 40°C is 0.70 to 3.00.

Fig. 1